# 2.5V Drive Pch MOSFET

# RTF010P02

#### ●Structure

Silicon P-channel MOSFET

#### ● Features

- 1) Low on-resistance. (570m $\Omega$  at 2.5V)
- 2) High power package.
- 3) High speed switching.
- 4) Low voltage drive. (2.5V)

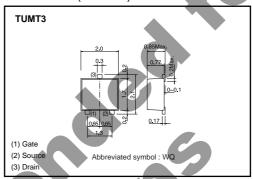
### Applications

DC-DC converter

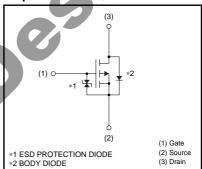
### Packaging specifications

	Package	Taping		
Type	Code	TL		
	Basic ordering unit (pieces)	3000		
RTF010P02	0			

#### ●Dimensions (Unit:mm)



# ●Equivalent circuit



# ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit	
Drain-source voltage		V <sub>DSS</sub>	-20	V	
Gate-source voltage		V <sub>GSS</sub>	±12	V	
Discharge and	Continuous	I <sub>D</sub>	±1	Α	
Drain current	Pulsed	I <sub>DP</sub> *1	±4	Α	
Source current (Body diode)	Continuous	Is *1	-0.4	Α	
	Pulsed	I <sub>SP</sub>	-4	Α	
Total power dissipation		P <sub>D</sub> *2	0.8	W	
Channel temperature	Tch	150	°C		
Range of Storage temperatu	Tstg	-55 to +150	°C		

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

### ●Thermal resistance

Parameter	Symbol	Limits	Unit
Channel to ambient	Rth(ch-a) *	156	°C / W

<sup>\*</sup> Mounted on a ceramic board.

Rev.C

#### ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Gate-source leakage	Igss	-	_	±10	μА	Vgs=±12V, Vps=0V
Drain-source breakdown voltage	$V_{(BR)\;DSS}$	-20	_	_	V	I <sub>D</sub> = -1mA, V <sub>GS</sub> =0V
Zero gate voltage drain current	I <sub>DSS</sub>	_	_	-1	μΑ	V <sub>DS</sub> = -20V, V <sub>GS</sub> =0V
Gate threshold voltage	V <sub>GS (th)</sub>	-0.7	_	-2.0	V	$V_{DS} = -10V, I_{D} = -1mA$
Static drain-source on-state resistance	*	-	280	390	mΩ	I <sub>D</sub> = -1A, V <sub>G</sub> S= -4.5V
	R <sub>DS (on)</sub>	-	310	430	mΩ	I <sub>D</sub> = -1A, V <sub>G</sub> S= -4V
resistance		-	570	800	mΩ	I <sub>D</sub> = -0.5A, V <sub>G</sub> S= -2.5V
Forward transfer admittance	Y <sub>fs</sub>  *	0.7	-	_	S	V <sub>DS</sub> = -10V, I <sub>D</sub> = -0.5A
Input capacitance	Ciss	_	150	_	pF	V <sub>DS</sub> = -10V
Output capacitance	Coss	_	20	_	pF	Vgs=0V
Reverse transfer capacitance	Crss	_	20	_	pF	f=1MHz
Turn-on delay time	t <sub>d (on)</sub> *	_	9	_	ns	ID= -0.5A
Rise time	tr *	-	8	_	ns	V <sub>DD</sub> = −15V V <sub>GS</sub> = −4.5V
Turn-off delay time	td (off) *	_	25	_	ns	$R_L=30\Omega$
Fall time	t <sub>f</sub> *	-	10	_	ns	R <sub>G</sub> =10Ω
Total gate charge	Qg *	-	2.1	_	nC	V <sub>DD</sub> ≒-15V R <sub>L</sub> =15Ω
Gate-source charge	Q <sub>gs</sub> *	_	0.5	-	nC	$V_{GS} = -4.5V$ Rg=10 $\Omega$
Gate-drain charge	Q <sub>gd</sub> *	_	0.5	_	nC	I <sub>D</sub> =-1A

\*Pulsed

# ●Body diode characteristics (Source -drain) (Ta=25°C)

						$\overline{}$	
	Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
	Forward voltage	Vsp	-		-1.2	V	I <sub>S</sub> = -0.4A, V <sub>G</sub> s=0V
Forward voltage VSD - J-2 V Is= -0.4A, Vas=UV							



#### •Electrical characteristic curves

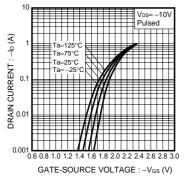


Fig.1 Typical Transfer Characteristics

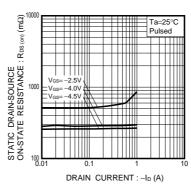


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current

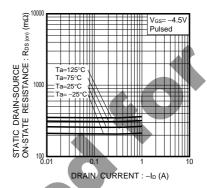


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current

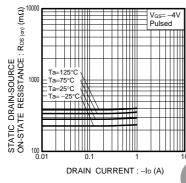


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current

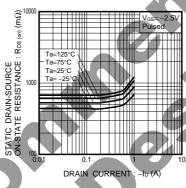


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current

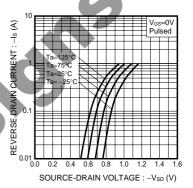


Fig.6 Reverse Drain Current vs. Source-Drain Voltage

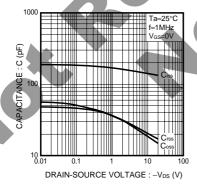


Fig.7 Typical Capacitance vs. Drain-Source Voltage

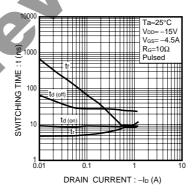


Fig.8 Switching Characteristics

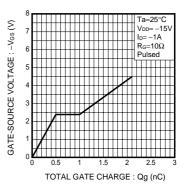


Fig.9 Dynamic Input Characteristics

#### ●Measurement circuits

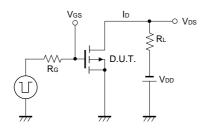


Fig.10 Switching Time Measurement Circuit

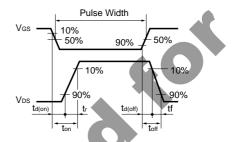


Fig.11 Switching Waveforms

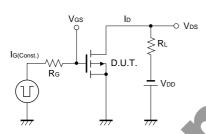


Fig.12 Gate Charge Measurement Circuit

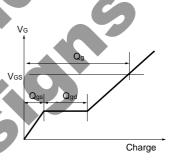


Fig.13 Gate Charge Waveforms

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